



SOT1045-1

plastic dual in-line compatible thermal enhanced extremely thin quad flat package; no leads; 20 terminals; UTLP based

5 February 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	DHXQFN20U
Package type industry code	DHXQFN20U
Package style descriptive code	DHXQFN (DIL-compatible thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-08-2009
Manufacturer package code	SOT1045

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.4	4.5	4.6	mm
package width	2.4	2.5	2.6	mm
seated height	-	-	0.5	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	20	-	



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2 Package outline

DHXQFN20U: plastic dual in-line compatible thermal enhanced extremely thin quad flat package; no leads; 20 terminals; UTLF based; body 2.5 x 4.5 x 0.5 mm

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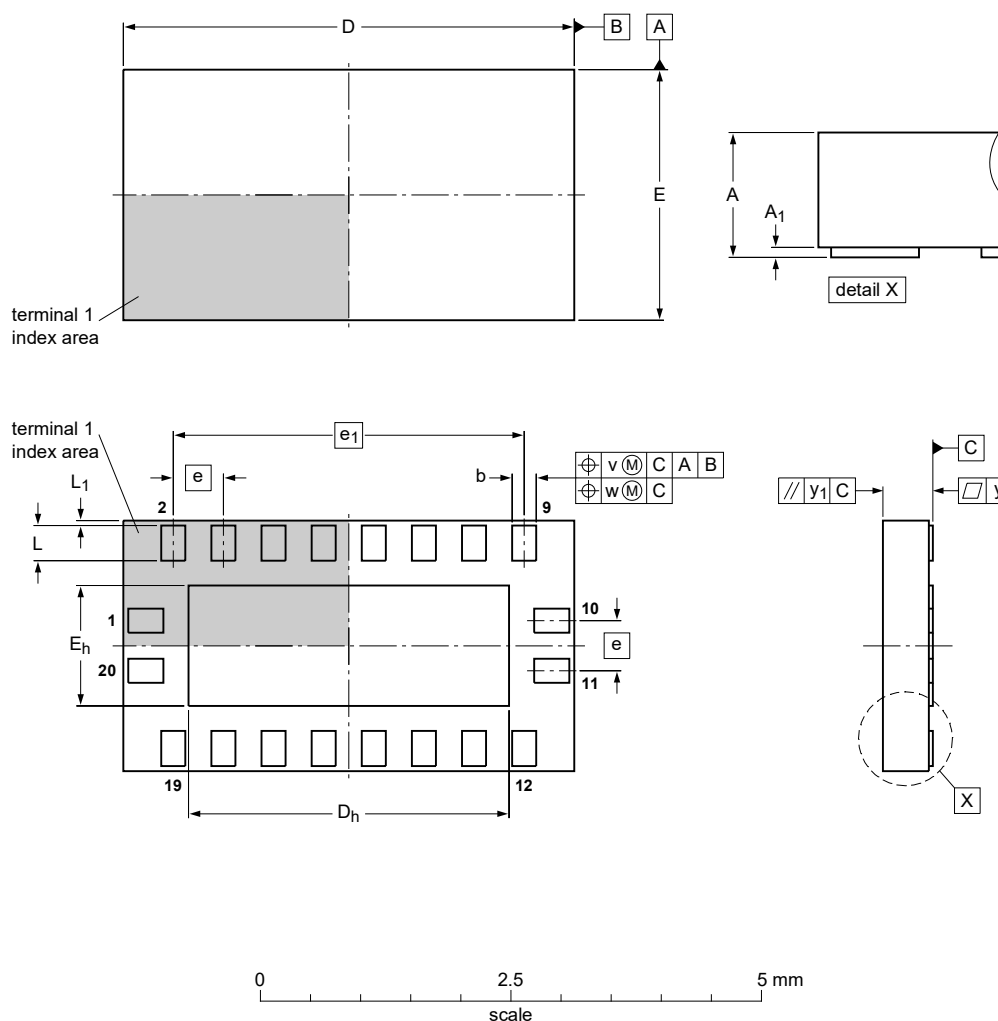


Figure 1. Package outline DHXQFN20U (SOT1045-1)

3 Legal information

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